



SPANSION LLC
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September 20, 2007

Obsolescence Notification No: 2659

Subject: **Obsolescence of the Type 2, 256 SDRAM Multi-Chip Packages (MCPs) products listed below**

Spansion LLC is announcing the obsolescence type 2, 256 SDRAM, and all valid combinations of the Multi-Chip Packages (MCPs) products listed below:

Product Identification: S72WS256NEEBAWUB, S72WS256NEEBFWUB, S98WS512NE0FW001, S98WS512PE0FW005

Package Types: TSB103, FT137

Product Line: WSD – Wireless Solutions Division

Description of Obsolescence: Obsolescence of MCP Ordering Part Numbers (OPNs), built with 256 SDRAM, Type 2.

Reason for Obsolescence: These products are being removed from Spansion's portfolio due to commercial die used in the MCPs being end-of-life by the commercial die supplier.

Application Impact: Consolidation of product offerings.

Replacement Parts: Please contact your Spansion sales representative for the appropriate replacement MCPs with SDRAM, type 5, or the next revision die of type 2 SDRAM.

Last Order Date March 20, 2008

Obsolescence No. 2659
09/20/07



Last Shipment Date: September 20, 2008

Products Affected By This Obsolescence (part numbers):

S72WS256NEEBAWUB

S72WS256NEEBFWUB0#

S98WS512NE0FW0010C

S72WS256NEEBFWUB0

S72WS256NEEBFWUB0G

S98WS512NE0FW0010G